L Number	Hits	Search Text	DB	Time stamp
1	852	kobayashi-shinji\$.in.	USPAT; US-PGPUB;	2004/09/02 13:51
			EPO; JPO; DERWENT; IBM TDB	
2	170	kitano-takahiro\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/02
3	147	sugimoto-shinichi\$.in.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/02 13:52
4	6717	(semiconductor or wafer or substrate or disk or disc) near13 (solvent near3 evaporat\$)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/02 13:53
5	1068824	vacuum or (reduced adj pressure) or (negative adj pressure)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/02 13:54
6	1151060	vacuum or (reduced adj pressure) or (negative adj pressure) or evacuat\$	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/02 13:59
7	2984	<pre>(vacuum or (reduced adj pressure) or (negative adj pressure) or evacuat\$) and ((semiconductor or wafer or substrate or disk or disc) near13 (solvent near3 evaporat\$))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/02 14:13
8	439	((vacuum or (reduced adj pressure) or (negative adj pressure) or evacuat\$) and ((semiconductor or wafer or substrate or disk or disc) near13 (solvent near3	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/02 14:16
9	1	evaporat\$))) and (solvent near3 reduc\$) (((vacuum or (reduced adj pressure) or (negative adj pressure) or evacuat\$) and ((semiconductor or wafer or substrate or disk or disc) near13 (solvent near3 evaporat\$))) and (solvent near3 reduc\$)) and (straighten\$ near3 vane)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 14:02
10	23032	(clamp or clamping) near3 (semiconductor or wafer or substrate or disk or disc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/02 14:03
11	4	<pre>(((vacuum or (reduced adj pressure) or (negative adj pressure) or evacuat\$) and ((semiconductor or wafer or substrate or disk or disc) near13 (solvent near3 evaporat\$))) and (solvent near3 reduc\$)) and ((clamp or clamping) near3 (semiconductor or wafer or substrate or disk or disc))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 14:05
12	7	("4633804" "5059266" "5578127" "5662785" "5804046" "6033480" "6063190").PN.	USPAT	2004/09/02 14:04
13	. 67	<pre>(((vacuum or (reduced adj pressure) or (negative adj pressure) or evacuat\$) and ((semiconductor or wafer or substrate or disk or disc) near13 (solvent near3 evaporat\$))) and (solvent near3 reduc\$)) and (aligner or alignment or aligning)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 14:18

14	208080	2004	T	
14	208080	control?\$4 near3 (pressure or vacuum\$ or	USPAT;	2004/09/02
		evacuat?\$3)	US-PGPUB;	14:14
			EPO; JPO;	
			DERWENT;	İ
			IBM TDB	
15	1390	(control?\$4 near3 (pressure or vacuum\$ or	USPAT;	2004/09/02
		evacuat?\$3)) and (solvent near3 reduc\$)	US-PGPUB;	14:17
	İ		EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	4411	(control?\$4 near3 (pressure or vacuum\$ or	USPAT;	2004/09/02
		evacuat?\$3)) and (solvent near3 remov?\$3)	US-PGPUB;	14:17
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
18	648	((control?\$4 near3 (pressure or vacuum\$	USPAT;	2004/09/02
		or evacuat?\$3)) and (solvent near3	US-PGPUB;	14:18
		remov?\$3)) and (aligner or alignment or	EPO; JPO;	
		aligning)	DERWENT;	
			IBM TDB	
17	116	((control?\$4 near3 (pressure or vacuum\$	USPAT;	2004/09/02
		or evacuat?\$3)) and (solvent near3	US-PGPUB;	14:18
		reduc\$)) and (aligner or alignment or	EPO; JPO;	
		aligning)	DERWENT:	
			IBM TDB	1